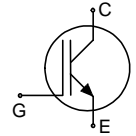
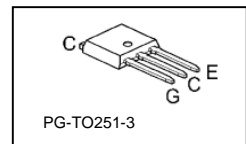


Low Loss IGBT : IGBT in TRENCHSTOP™ technology



- Very low  $V_{CE(sat)}$  1.5 V (typ.)
- Maximum Junction Temperature 175°C
- Short circuit withstand time 5 $\mu$ s
- Designed for :
  - frequency inverters
  - drives
- TRENCHSTOP™ technology for 600V applications offers :
  - very tight parameter distribution
  - high ruggedness, temperature stable behavior
  - very high switching speed
  - low  $V_{CE(sat)}$
- Positive temperature coefficient in  $V_{CE(sat)}$
- Low EMI
- Low Gate Charge
- Qualified according to JEDEC<sup>1</sup> for target applications
- Complete product spectrum and PSpice Models : <http://www.infineon.com/igbt/>



Type	$V_{CE}$	$I_C$	$V_{CE(sat), T_j=25^\circ C}$	$T_{j,max}$	Marking	Package
IGU04N60T	600 V	4 A	1.5 V	175 °C	G04T60	PG-TO251-3

### Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{CE}$	600	V
DC collector current, limited by $T_{j,max}$ $T_C = 25^\circ C$ $T_C = 100^\circ C$	$I_C$	8 4	A
Pulsed collector current, $t_p$ limited by $T_{j,max}$	$I_{C,puls}$	12	
Turn off safe operating area ( $V_{CE} \leq 600V, T_j \leq 175^\circ C$ )	-	12	
Gate-emitter voltage	$V_{GE}$	$\pm 20$	V
Short circuit withstand time <sup>2)</sup> $V_{GE} = 15V, V_{CC} \leq 400V, T_j \leq 150^\circ C$	$t_{SC}$	5	$\mu s$
Power dissipation $T_C = 25^\circ C$	$P_{tot}$	42	W
Operating junction temperature	$T_j$	-40...+175	$^\circ C$
Storage temperature	$T_{stg}$	-55...+150	
Soldering temperature, wave soldering, 1.6mm (0.063 in.) from case for 10s.	$T_s$	260	$^\circ C$

<sup>1</sup> J-STD-020 and JESD-022

<sup>2)</sup> Allowed number of short circuits: <1000; time between short circuits: >1s.

### Thermal Resistance

Parameter	Symbol	Conditions	Max. Value	Unit
<b>Characteristic</b>				
IGBT thermal resistance, junction – case	$R_{thJC}$		3.5	K/W
Thermal resistance, junction – ambient	$R_{thJA}$		75	

### Electrical Characteristic, at $T_j = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	Typ.	max.	
<b>Static Characteristic</b>						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0V, I_C=0.2mA$	600	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15V, I_C=4A$ $T_j=25^\circ\text{C}$ $T_j=175^\circ\text{C}$	-	1.5 1.9	2.05 -	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C = 60\mu A, V_{CE}=V_{GE}$	4.1	4.9	5.7	
Zero gate voltage collector current	$I_{CES}$	$V_{CE}=600V,$ $V_{GE}=0V$ $T_j=25^\circ\text{C}$ $T_j=175^\circ\text{C}$	-	- 40	40 -	$\mu A$
Gate-emitter leakage current	$I_{GES}$	$V_{CE}=0V, V_{GE}=20V$	-	-	100	nA
Transconductance	$g_{fs}$	$V_{CE}=20V, I_C=4A$	-	2.2	-	S

### Dynamic Characteristic

Input capacitance	$C_{iss}$	$V_{CE}=25V,$ $V_{GE}=0V,$ $f=1MHz$	-	252	-	pF
Output capacitance	$C_{oss}$		-	20	-	
Reverse transfer capacitance	$C_{rss}$		-	7.5	-	
Gate charge	$Q_{Gate}$	$V_{CC}=480V, I_C=4A$ $V_{GE}=15V$	-	27	-	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	$L_E$		-	7	-	nH
Short circuit collector current <sup>1)</sup>	$I_{C(SC)}$	$V_{GE}=15V, t_{SC}\leq 5\mu s$ $V_{CC} = 400V,$ $T_j \leq 150^\circ\text{C}$	-	36	-	A

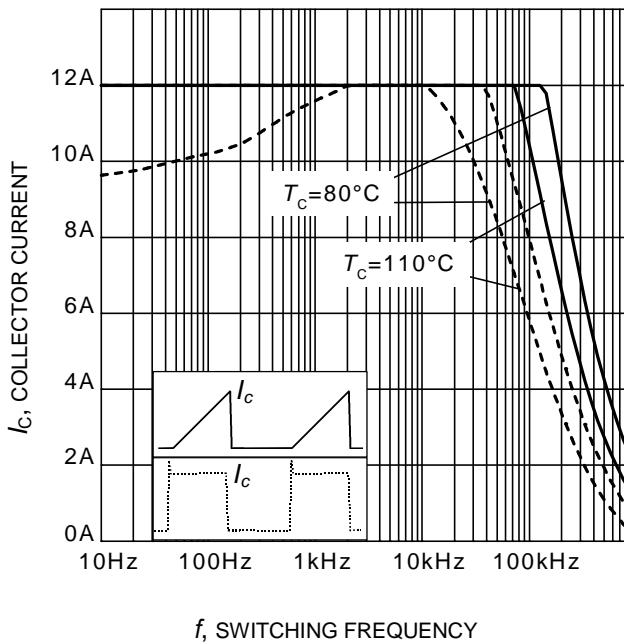
<sup>1)</sup> Allowed number of short circuits: <1000; time between short circuits: >1s.

### Switching Characteristic, Inductive Load, at $T_j=25^\circ\text{C}$

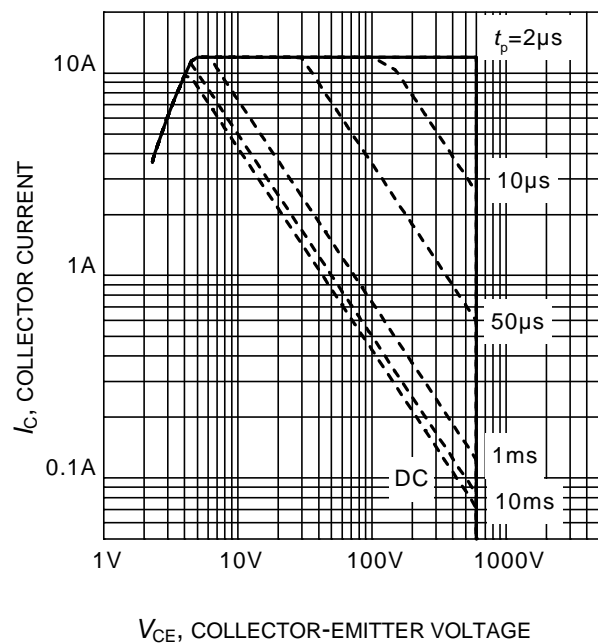
Parameter	Symbol	Conditions	Value			Unit
			min.	Typ.	max.	
<b>IGBT Characteristic</b>						
Turn-on delay time	$t_{d(on)}$	$T_j=25^\circ\text{C}$ , $V_{CC}=400\text{V}$ , $I_C=4\text{A}$ , $V_{GE}=0/15\text{V}$ , $r_G=47\Omega$ , $L_\sigma=150\text{nH}$ , $C_\sigma=47\text{pF}$ $L_\sigma$ , $C_\sigma$ from Fig. E Energy losses include "tail" and diode reverse recovery.	-	14	-	ns
Rise time	$t_r$		-	7	-	
Turn-off delay time	$t_{d(off)}$		-	164	-	
Fall time	$t_f$		-	43	-	
Turn-on energy	$E_{on}$		-	61	-	$\mu\text{J}$
Turn-off energy	$E_{off}$		-	84	-	
Total switching energy	$E_{ts}$		-	145	-	

### Switching Characteristic, Inductive Load, at $T_j=175^\circ\text{C}$

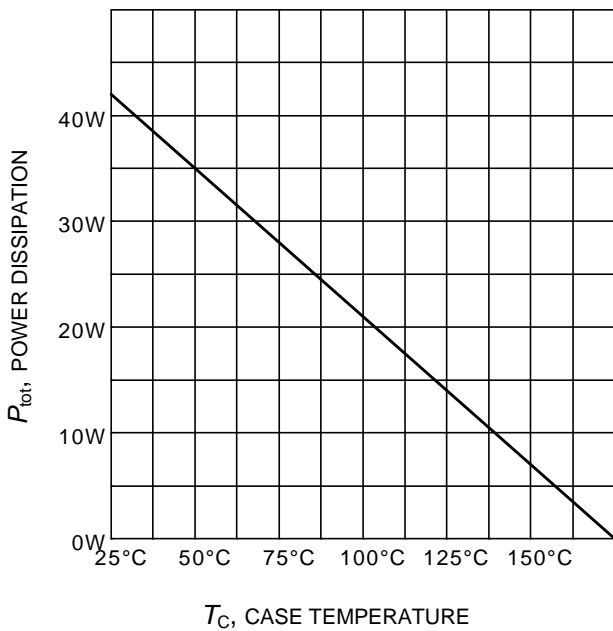
Parameter	Symbol	Conditions	Value			Unit
			min.	Typ.	max.	
<b>IGBT Characteristic</b>						
Turn-on delay time	$t_{d(on)}$	$T_j=175^\circ\text{C}$ , $V_{CC}=400\text{V}$ , $I_C=4\text{A}$ , $V_{GE}=0/15\text{V}$ , $r_G=47\Omega$ , $L_\sigma=150\text{nH}$ , $C_\sigma=47\text{pF}$ $L_\sigma$ , $C_\sigma$ from Fig. E Energy losses include "tail" and diode reverse recovery.	-	14	-	ns
Rise time	$t_r$		-	10	-	
Turn-off delay time	$t_{d(off)}$		-	185	-	
Fall time	$t_f$		-	83	-	
Turn-on energy	$E_{on}$		-	99	-	$\mu\text{J}$
Turn-off energy	$E_{off}$		-	97	-	
Total switching energy	$E_{ts}$		-	196	-	



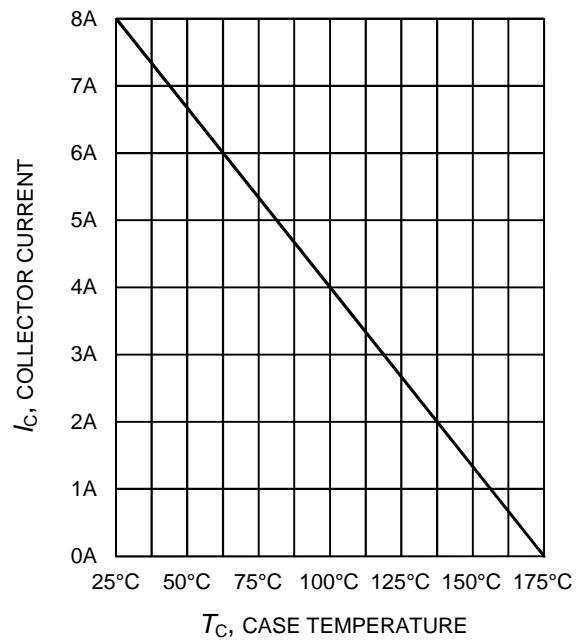
**Figure 1. Collector current as a function of switching frequency**  
 ( $T_j \leq 175^\circ\text{C}$ ,  $D = 0.5$ ,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/15\text{V}$ ,  $r_G = 47\Omega$ )



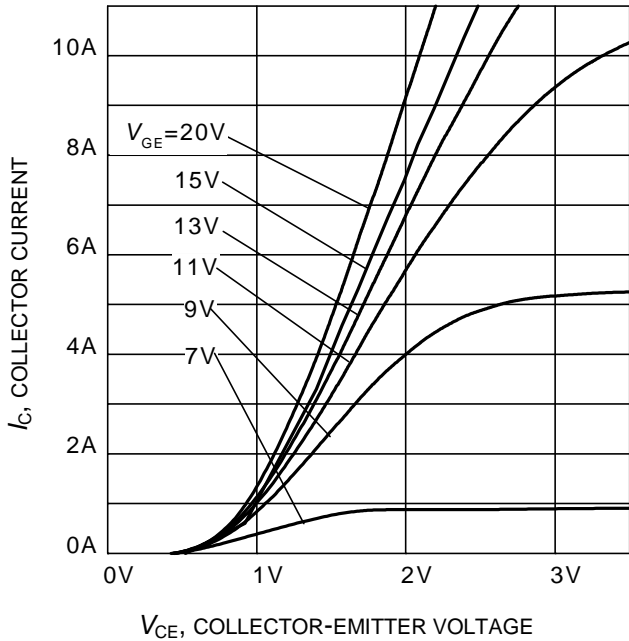
**Figure 2. Safe operating area**  
 ( $D = 0$ ,  $T_C = 25^\circ\text{C}$ ,  $T_j \leq 175^\circ\text{C}$ ;  $V_{GE} = 0/15\text{V}$ )



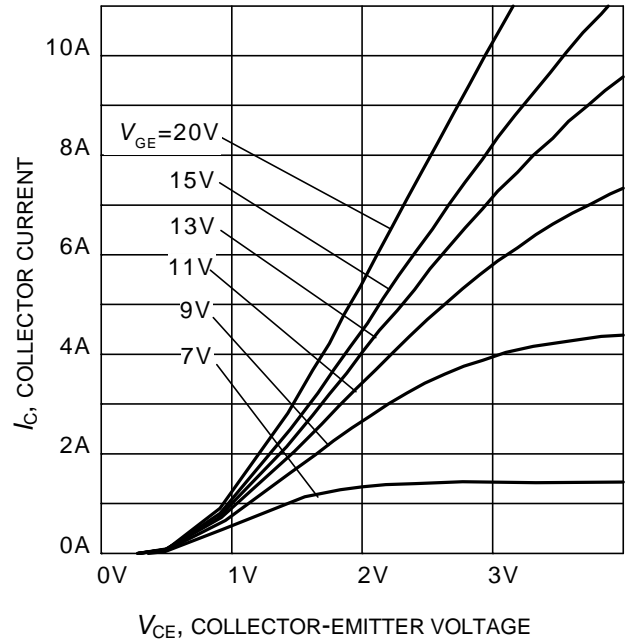
**Figure 3. Power dissipation as a function of case temperature**  
 ( $T_j \leq 175^\circ\text{C}$ )



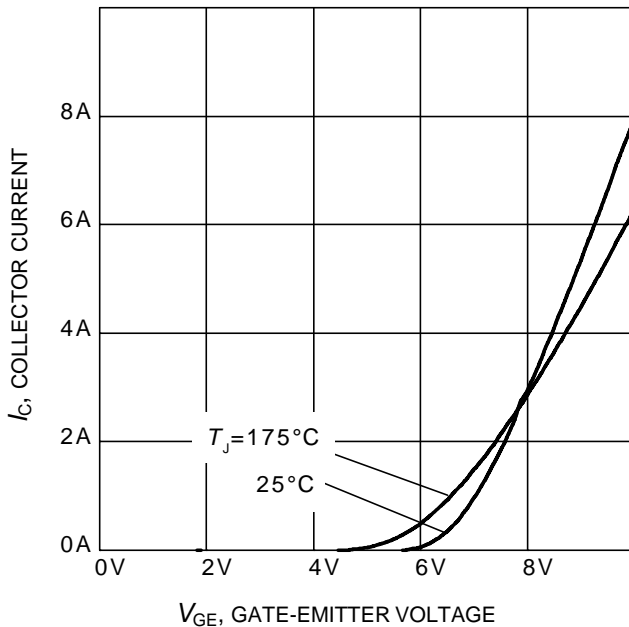
**Figure 4. Collector current as a function of case temperature**  
 ( $V_{GE} \geq 15\text{V}$ ,  $T_j \leq 175^\circ\text{C}$ )



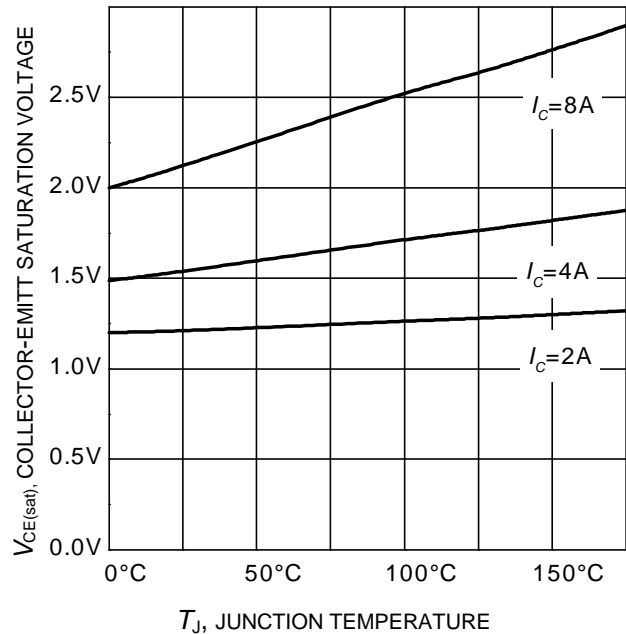
**Figure 5. Typical output characteristic**  
( $T_j = 25^\circ\text{C}$ )



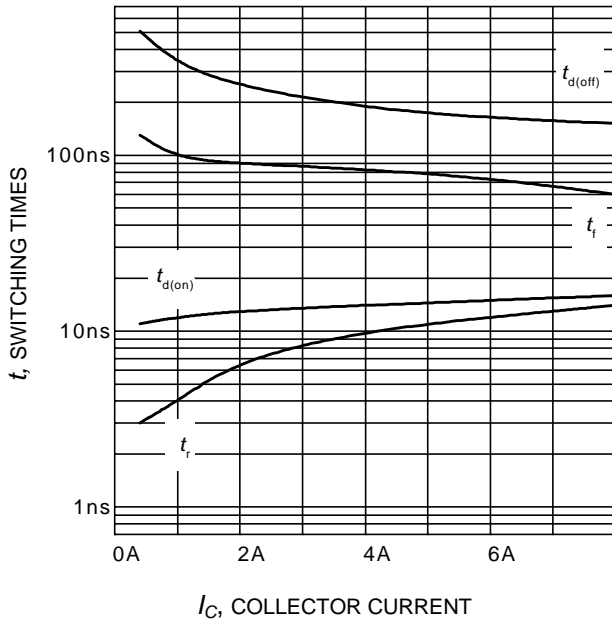
**Figure 6. Typical output characteristic**  
( $T_j = 175^\circ\text{C}$ )



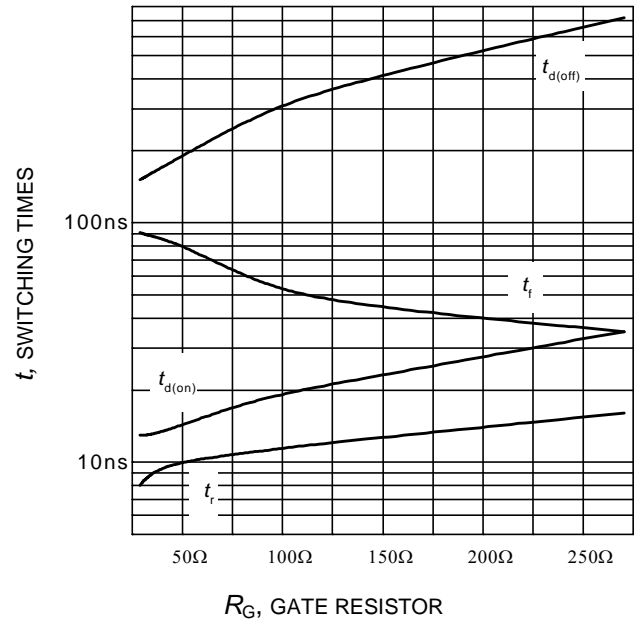
**Figure 7. Typical transfer characteristic**  
( $V_{CE} = 20\text{V}$ )



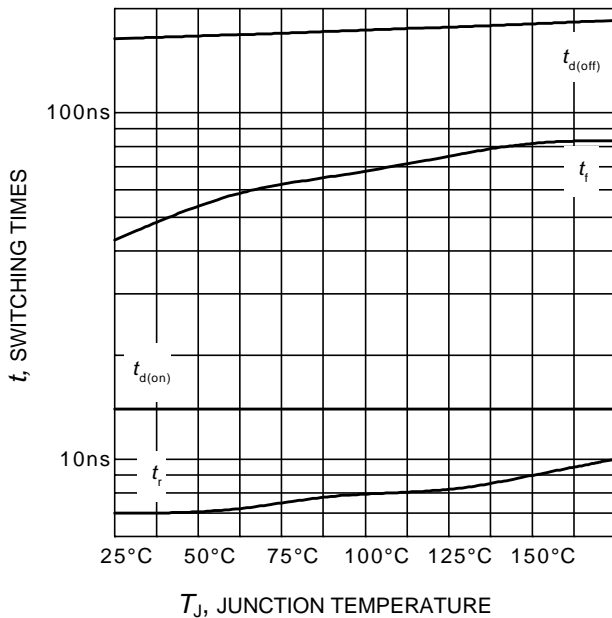
**Figure 8. Typical collector-emitter saturation voltage as a function of junction temperature**  
( $V_{GE} = 15\text{V}$ )



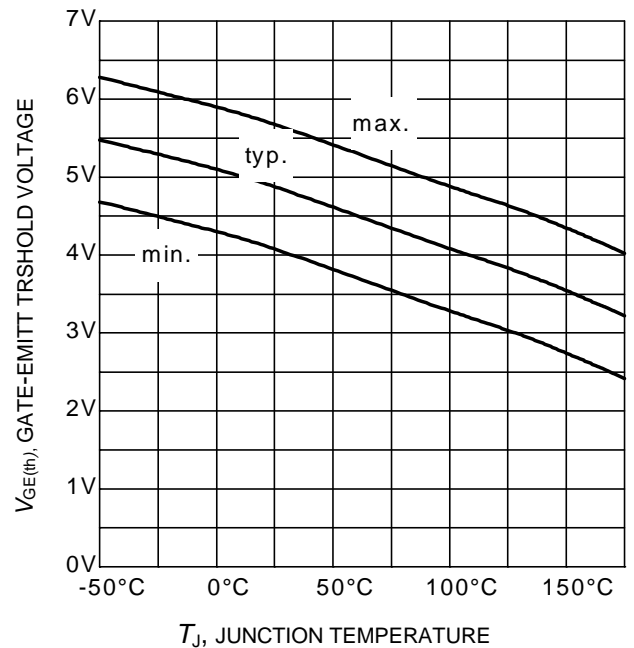
**Figure 9. Typical switching times as a function of collector current**  
 (inductive load,  $T_J=175^\circ\text{C}$ ,  
 $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/15\text{V}$ ,  $r_G = 47\Omega$ ,  
 Dynamic test circuit in Figure E)



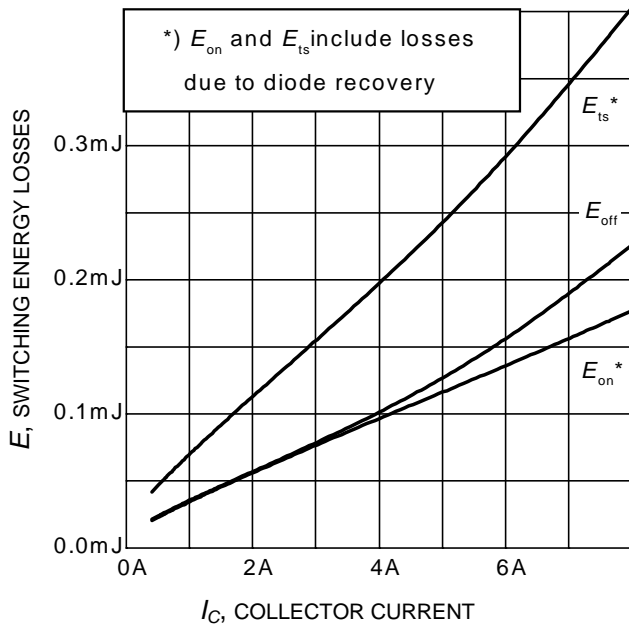
**Figure 10. Typical switching times as a function of gate resistor**  
 (inductive load,  $T_J = 175^\circ\text{C}$ ,  
 $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/15\text{V}$ ,  $I_C = 4\text{A}$ ,  
 Dynamic test circuit in Figure E)



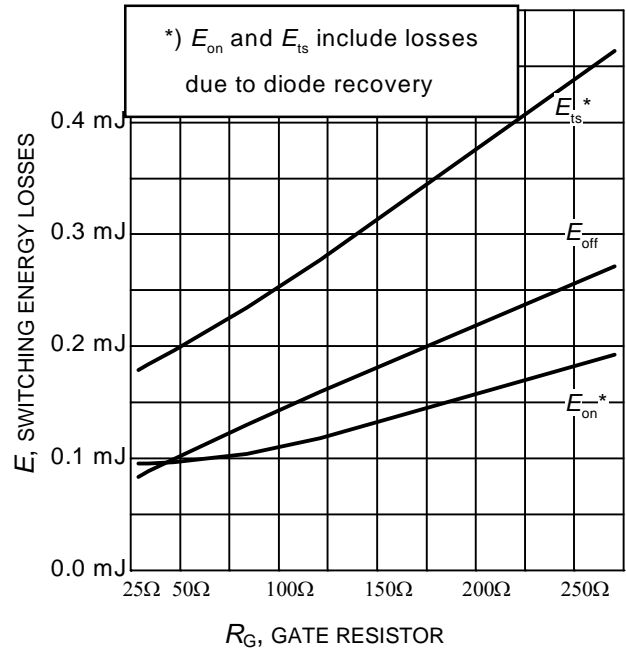
**Figure 11. Typical switching times as a function of junction temperature**  
 (inductive load,  $V_{CE} = 400\text{V}$ ,  
 $V_{GE} = 0/15\text{V}$ ,  $I_C = 4\text{A}$ ,  $r_G = 47\Omega$ ,  
 Dynamic test circuit in Figure E)



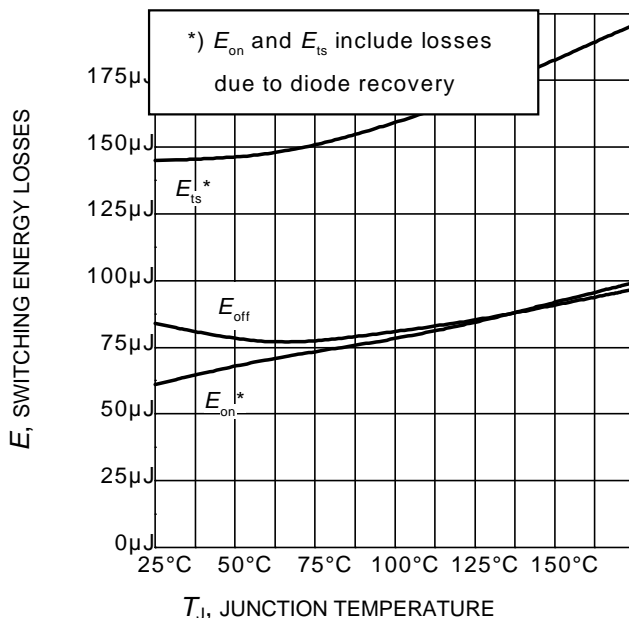
**Figure 12. Gate-emitter threshold voltage as a function of junction temperature**  
 ( $I_C = 60\ \mu\text{A}$ )



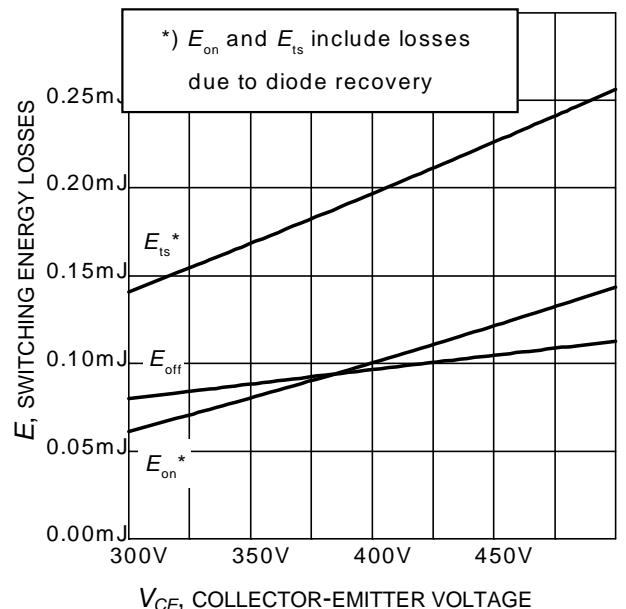
**Figure 13. Typical switching energy losses as a function of collector current**  
 (inductive load,  $T_J = 175^\circ\text{C}$ ,  
 $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/15\text{V}$ ,  $r_G = 47\Omega$ ,  
 Dynamic test circuit in Figure E)



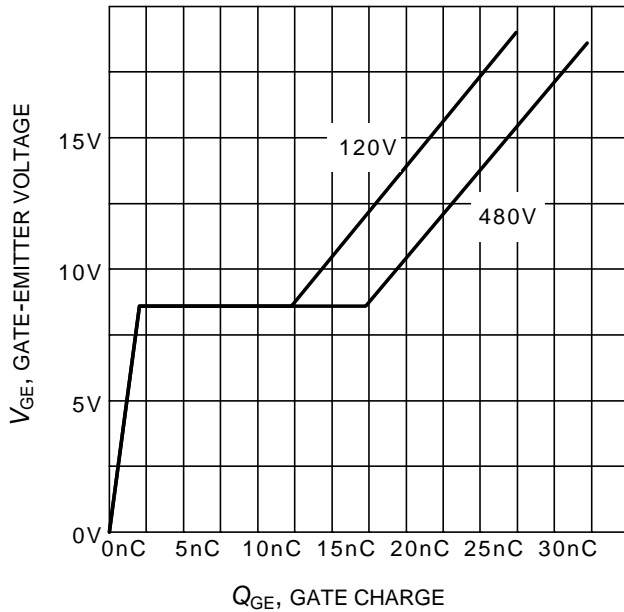
**Figure 14. Typical switching energy losses as a function of gate resistor**  
 (inductive load,  $T_J = 175^\circ\text{C}$ ,  
 $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/15\text{V}$ ,  $I_C = 4\text{A}$ ,  
 Dynamic test circuit in Figure E)



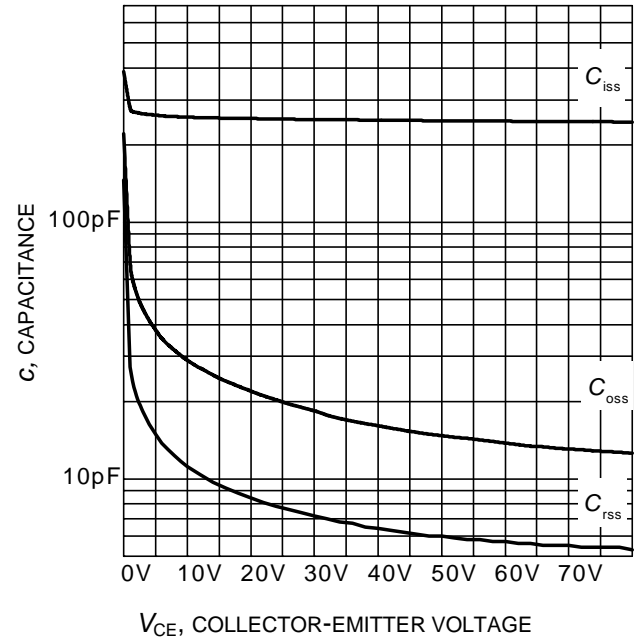
**Figure 15. Typical switching energy losses as a function of junction temperature**  
 (inductive load,  $V_{CE} = 400\text{V}$ ,  
 $V_{GE} = 0/15\text{V}$ ,  $I_C = 4\text{A}$ ,  $r_G = 47\Omega$ ,  
 Dynamic test circuit in Figure E)



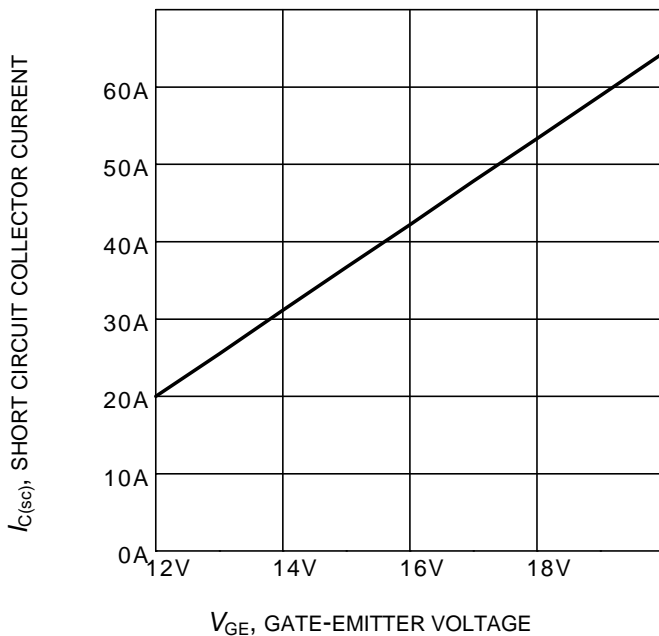
**Figure 16. Typical switching energy losses as a function of collector emitter voltage**  
 (inductive load,  $T_J = 175^\circ\text{C}$ ,  
 $V_{GE} = 0/15\text{V}$ ,  $I_C = 4\text{A}$ ,  $r_G = 47\Omega$ ,  
 Dynamic test circuit in Figure E)



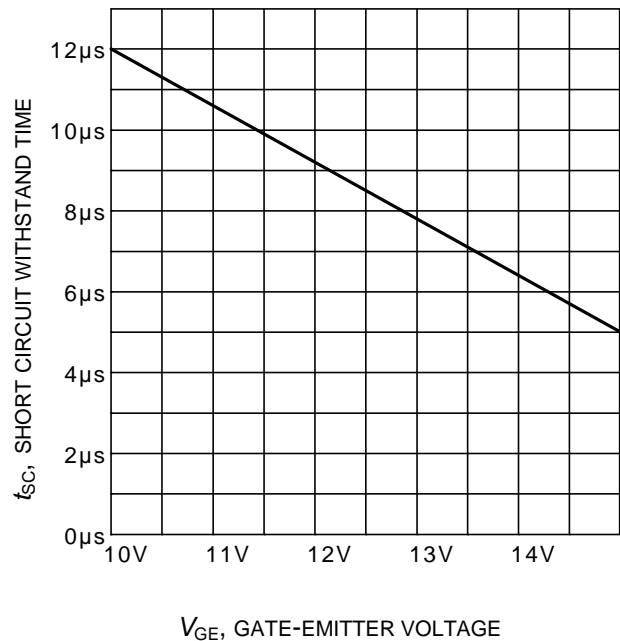
**Figure 17. Typical gate charge**  
( $I_C=4\text{ A}$ )



**Figure 18. Typical capacitance as a function of collector-emitter voltage**  
( $V_{GE}=0\text{V}$ ,  $f=1\text{ MHz}$ )

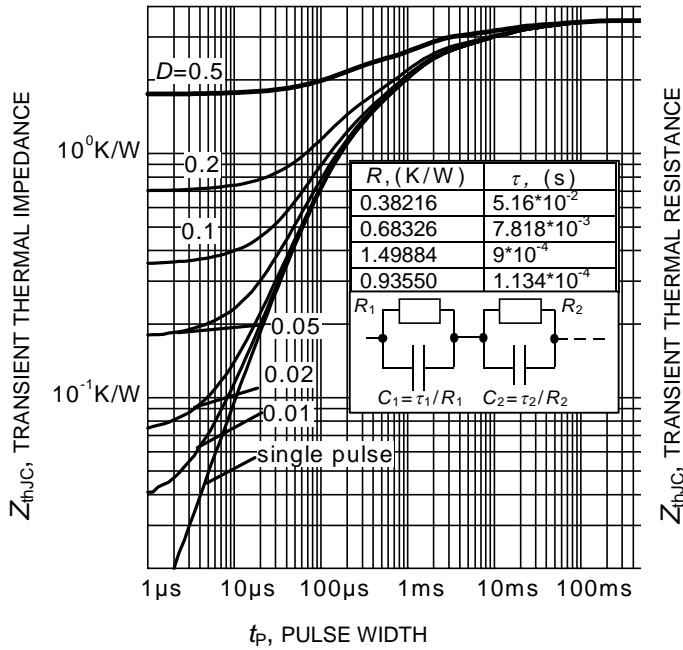


**Figure 19. Typical short circuit collector current as a function of gate-emitter voltage**  
( $V_{CE} \leq 400\text{V}$ ,  $T_j \leq 150^\circ\text{C}$ )



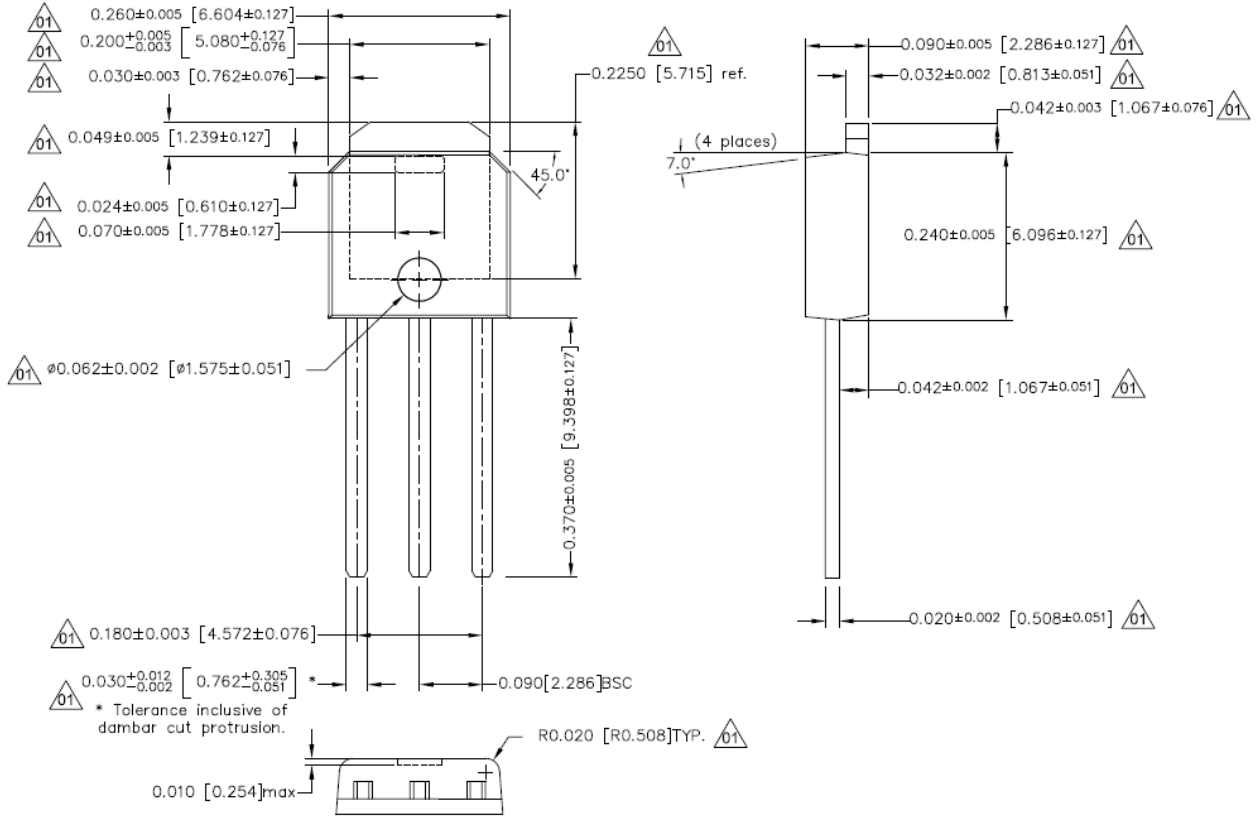
**Figure 20. Short circuit withstand time as a function of gate-emitter voltage**  
( $V_{CE}=400\text{V}$ , start at  $T_j=25^\circ\text{C}$ ,  $T_{j,max}<150^\circ\text{C}$ )

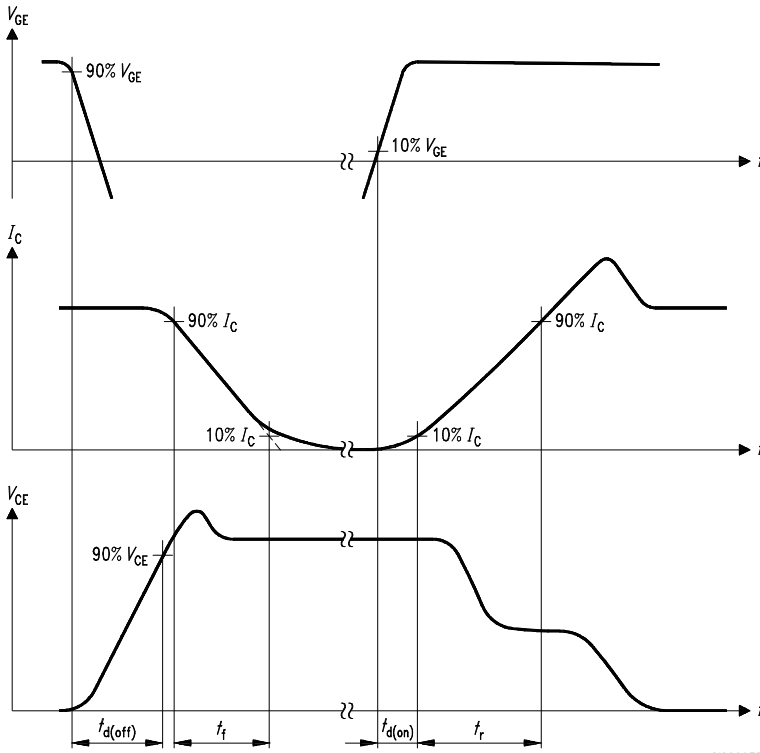




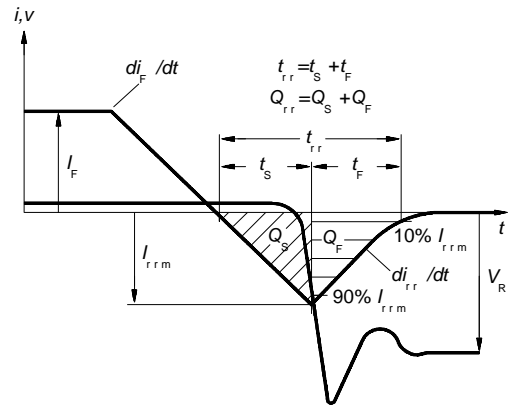
**Figure 21. IGBT transient thermal impedance**  
 $(D = t_p / T)$

### PG-TO251-3

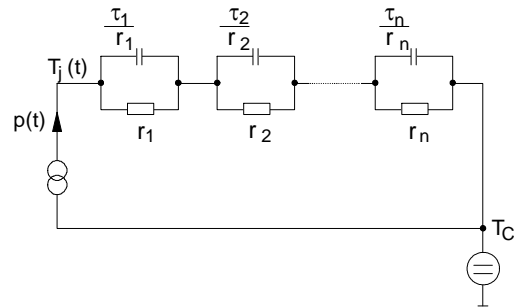




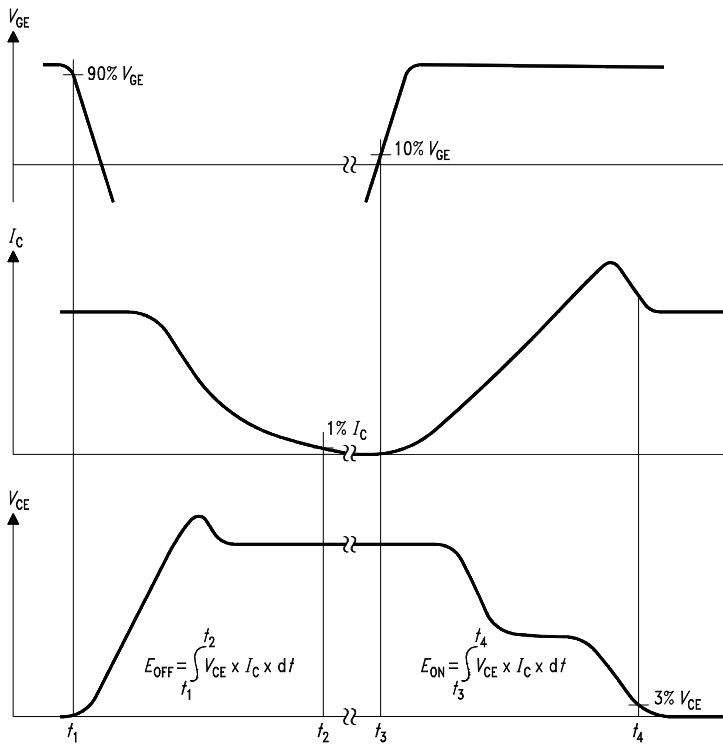
**Figure A. Definition of switching times**



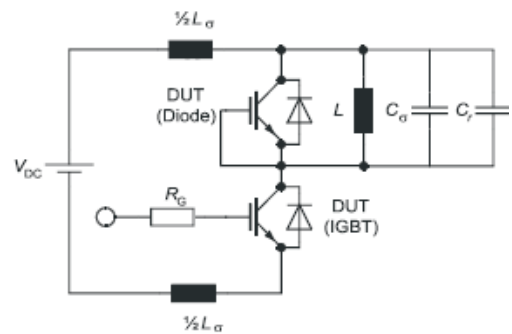
**Figure C. Definition of diodes switching characteristics**



**Figure D. Thermal equivalent circuit**



**Figure B. Definition of switching losses**



**Figure E. Dynamic test circuit**  
Parasitic inductance  $L_\sigma$ ,  
Parasitic capacitor  $C_\sigma$ ,  
Relief capacitor  $C_r$   
(only for ZVT switching)

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